

32K x 8 CMOS STATIC RAM

PRELIMINARY DATA

- BYTEWYDE™ 32K X 8 CMOS SRAM
- EQUAL CYCLE/ACCESS TIMES, 100, 120NS MAX.
- LOW V_{CC} DATA RETENTION, 2 VOLTS
- THREE-STATE OUTPUT

DESCRIPTION

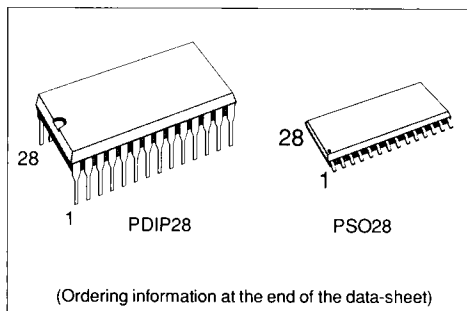
The MK48256 is a 256K (262,144-bit) CMOS SRAM, organized as 32,768 words x 8 bits. It is fabricated using SGS-THOMSON's low power, high performance, CMOS technology. The device features fully static operation requiring no external clocks or timing strobes, with equal address access and cycle times. It requires a single $+5V \pm 10\%$ supply, and all inputs and outputs are TTL compatible.

OPERATIONAL MODES

The MK48256 has a Chip Enable power down feature which sustains an automatic standby mode whenever Chip Enable ($\bar{E}$) goes inactive high. An Output Enable ($\bar{G}$) pin provides a high speed tristate control, allowing fast read/write cycles to be achieved with the common I/O data bus. Operational modes are determined by device control inputs $\bar{W}$, $\bar{G}$ and $\bar{E}$, as summarized in the truth table.

PIN NAMES

A0-A14	Address Inputs
DQ0-DQ7	Data I/O ₀₋₇
$\bar{E}$	Chip Enable
$\bar{G}$	(OE) Output Enable
$\bar{W}$	Write/Read Enable
V_{CC}	+ 5V
V_{SS}	GROUND



Pin Connection

A14	1	28	V_{CC}
A12	2	27	$\bar{W}$
A7	3	26	A13
A6	4	25	A8
A5	5	24	A9
A4	6	23	A11
A3	7	22	$\bar{G}$
A2	8	21	A10
A1	9	20	$\bar{E}$
A0	10	19	DQ ₇
DQ ₀	11	18	DQ ₆
DQ ₁	12	17	DQ ₅
DQ ₂	13	16	DQ ₄
V_{SS}	14	15	DQ ₃

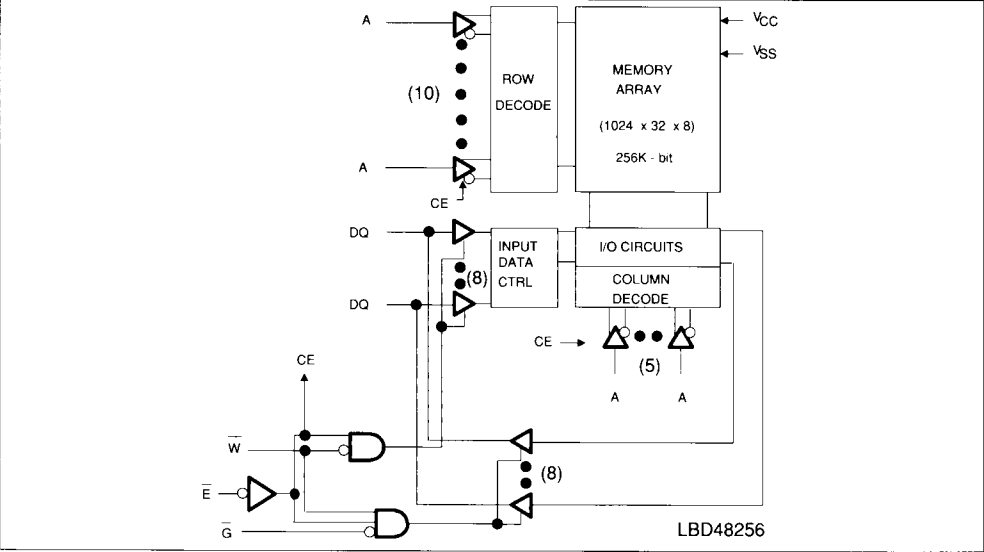
MK48256

VPR00030

MK48256 TRUTH TABLE

$\bar{E}$	$\bar{W}$	$\bar{G}$	MODE	DQ	POWER
H	X	X	Deselect	Hi-Z	Standby
L	H	H	Read	Hi-Z	Active
L	H	L	Read	D _{OUT}	Active
L	L	X	write	D _{IN}	Active

Figure 1 : MK48256 Block Diagram



READ MODE

The MK48256 is in the Read mode whenever Write Enable ($\overline{W}$) is high with Output Enable ($\overline{G}$) low, and Chip Enable ($\overline{E}$) is active low. This provides access to data from eight of 262,144 locations in the static memory array, specified by the 15 address inputs. Valid data will be available at the eight Output pins

within t_{AVQV} after the last stable address, providing $\overline{G}$ is low, and $\overline{E}$ is low. If Chip Enable or Output Enable access times are not met, data access will be measured from the limiting parameter (t_{ELQV} , or t_{GLQV}) rather than the address. Data out may be indeterminate at t_{ELQX} , and t_{GLQX} , but data lines will always be valid at t_{AVQV} .

AC ELECTRICAL CHARACTERISTICS (READ CYCLE)

(0°C ≤ T_A ≤ +70°C, V_{CC} = 5. V ± 10%)

SYMBOL	PARAMETER	MK48256-100		MK48256-120		UNIT	NOTE
		MIN	MAX	MIN	MAX		
t _{AVAV}	Read Cycle Time	100		120		ns	
t _{AVQV}	Address Access Time		100		120		4
t _{ELQV}	Chip Enable Access Time		100		120		4
t _{GLQV}	Output Enable Access Time		50		60		4
t _{ELQX}	Chip Enable to Q Low-Z	10		10			5
t _{GLQX}	Output Enable to Q Low-Z	5		5			5
t _{EHQZ}	Chip Disable ($\overline{E}$) High to Q High-Z	0	35	0	35		5
t _{GHQX}	Output Disable ($\overline{G}$) High to Q High-Z	0	35	0	35		5
t _{AXQX}	Output Hold from Address Change	10		10			4

NOTES : 4. Measured with load as shown in Figure 8A.
5. Measured with load as shown in Figure 8B.

Figure 2 : Read Timing N°.1 (Address Access)

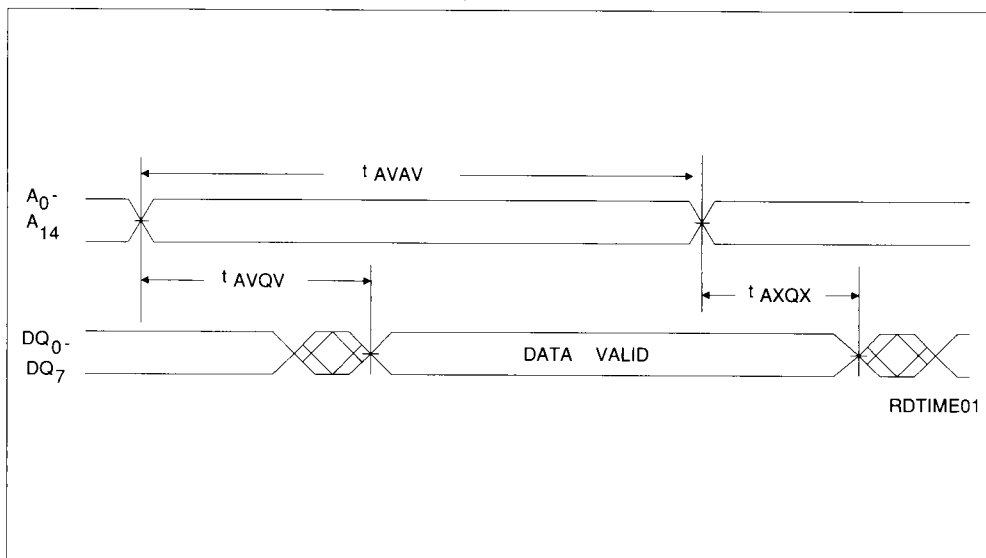
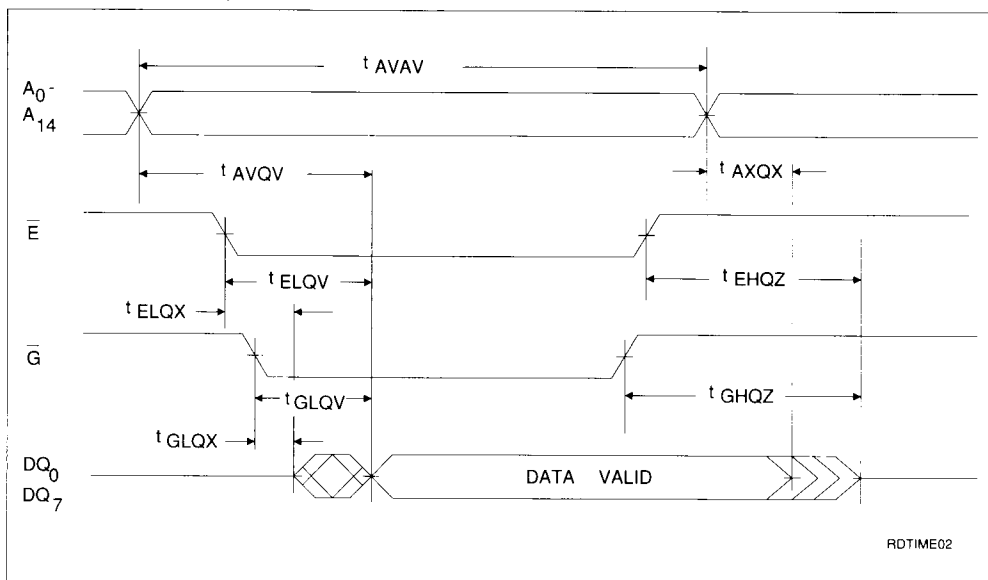
NOTE : $\bar{E} = \bar{G} = \text{Low}$, $\bar{W} = \text{High}$

Figure 3 : Read Timing N°.2

NOTE : $\bar{W} = \text{High}$

WRITE MODE

The MK48256 is in the Write mode whenever the $\overline{W}$ and $\overline{E}$ pins are low. Either Chip Enable or $\overline{W}$ must be inactive during Address transitions. The Write begins with the concurrence of Chip Enable being low with $\overline{W}$ low. Therefore, address setup times are referenced to Write Enable and Chip Enable as t_{AVWL} , and t_{AVEL} respectively, and is determined by whichever edge occurs latter. The Write cycle can be terminated by the earliest rising edge of $\overline{W}$ or Chip Enable ($\overline{E}$).

If the Output is enabled ($\overline{E}$ = low, $\overline{G}$ = low), then $\overline{W}$ will return the outputs to high impedance within t_{WLQZ} of its falling edge. Care must be taken to avoid bus contention in this type of operation. Data-in must be valid for t_{pVWH} to the rising edge of Write Enable, or to the rising edge of $\overline{E}$, whichever occurs first, and remain valid t_{WHDX} .

AC ELECTRICAL CHARACTERISTICS (WRITE CYCLE)

(0°C ≤ TA ≤ 70°C, VCC= 5.0 ±10%)

SYMBOL	PARAMETER	MK48256-100		MM48256-120		UNIT	NOTE
		MIN	MAX	MIN	MAX		
tAVAV	Write Cycle Time	100		120		ns	
tAVWL	Address Set-up Time to $\overline{W}$ Low	0		0			
tAVEL	Address Set-up Time to $\overline{E}$ Low	0		0			
tAVWH	address valid to $\overline{W}$ HiGh	80		85			
tWLWH	Write Pulse Width	60		65			
tWHAX	Address Hold After End Of Write	5		5			
tELEH	Chip Enable Active To End Of Write	80		85			
tEHAX	Address Hold Time From Chip Enable	5		5			
tDVWH	Data Valid To End Of Write	40		45			
tWHDX	Data Hold Time	0		0			
tWHQX	$\overline{W}$ High to Q Active	5		5			5
tWLQZ	$\overline{W}$ Low to Q High-Z	0	35	0	40		5

NOTE : 5. Measured with load as shown in Figure 8B.

Figure 4 : Write Control Cycle Timing

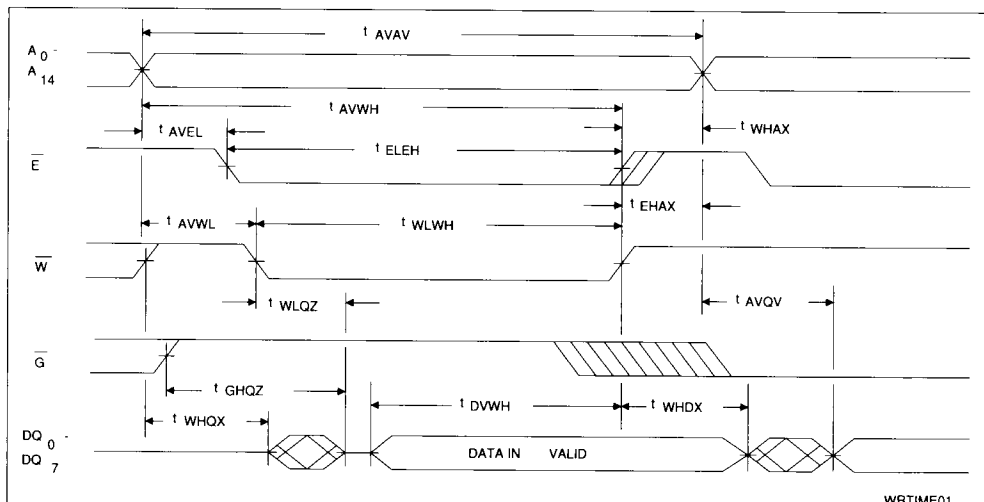
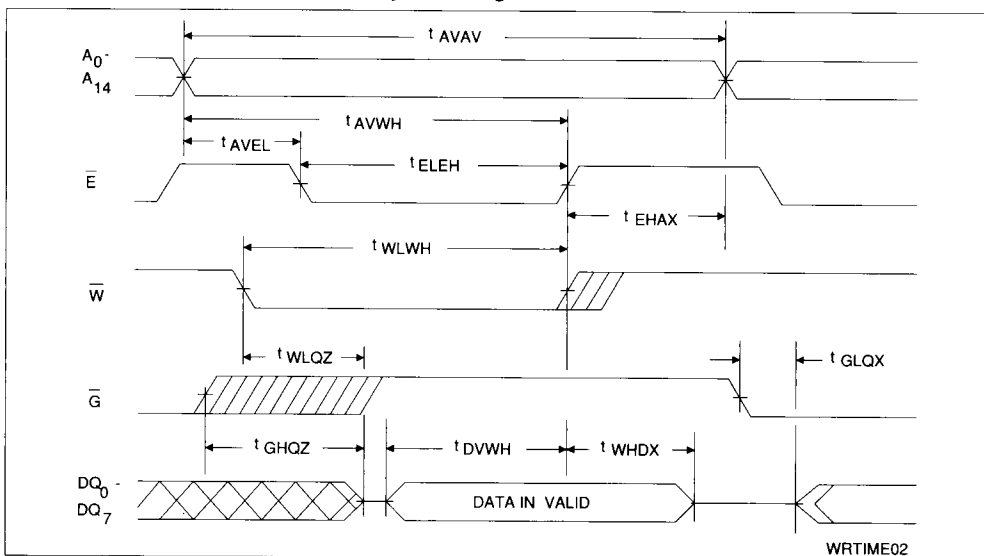


Figure 5 : Chip Enable Control Write Cycle Timing



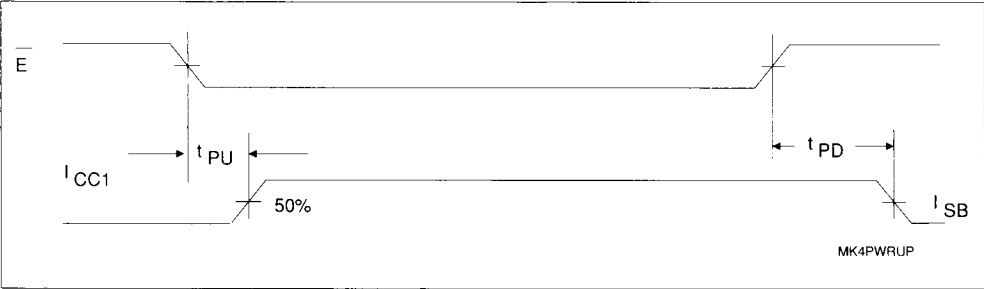
STANDBY MODE CHARACTERISTICS

(0°C ≤ TA ≤ +70°C, Vcc = 5.0V ± 10%)

SYMBOL	PARAMETER	MK48256-100		MK48256-120		UNIT
		MAX	MIN	MAX	MIN	
tPU †	Chip Enable to Power-Up	0		0		ns
tPD †	Chip Enable to Power-Down		100		120	ns

† Parameters are guaranteed but not tested.

Figure 6 : Standby Mode Timing



LOW Vcc DATA RETENTION CHARACTERISTICS

(0°C ≤ TA ≤ +70°C, Vcc = 5.0 ± 10%)

SYMBOL	PARAMETER		MAX	MAX	UNIT	NOTE
VDR	Vcc Data Retention Mode		2.0		V	9
IccDR ⁽¹⁾	Data Retention Pwr.supply Current Test Condition : Vcc = 3.0	MK48256		500	μA	9
		MK48256L		50	μA	9
tCDR †	Chip Deselect to Data Retention Mode		0		nS	9
tR †	Operation Recovery Time		tAVAV ⁽²⁾		nS	9

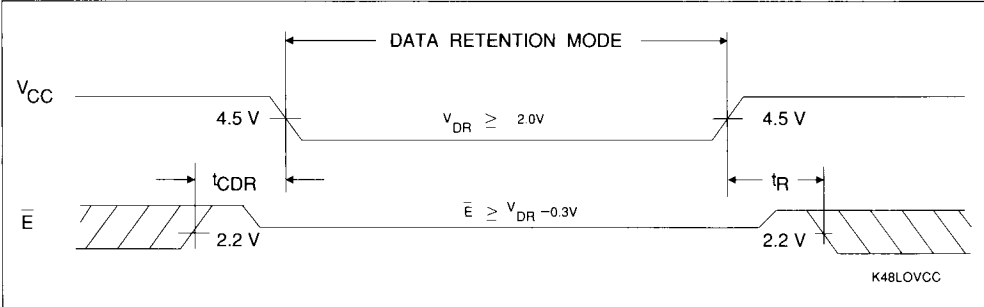
NOTE : 9. $\bar{E} \geq V_{cc} - 0.3v$, all other inputs = don't care ; f = 0

† Parameters are guaranteed but not tested.

⁽¹⁾ For IccDR between Vcc (MIN.) and Vcc (MAX.) refer to ISB1.

⁽²⁾ tAVAV = Read Cycle Time.

Figure 7 : Low Vcc Data Retention



ABSOLUTE MAXIMUM RATINGS *

SYMBOL	PARAMETER	VALUE	UNIT
V_I	Voltage On Any Pin Relative to Ground	-0.5 to +7.0	V
T_A	Ambient Operating Temperature	0 to 70	°C
T_{STG}	Storage Temperature	-65 to 150	°C
P_D	Power Dissipation	1	W
I_O	Output Current †	50	mA

* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

† Output current absolute maximum rating is specified for one output at a time, not to exceed a duration of 1 second.

RECOMMENDED DC OPERATING CONDITIONS

(0°C ≤ T_A ≤ +70°C)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	NOTE
V_{CC}	Supply Voltage	4.5	5.0	5.5	V	1
V_{SS}	Ground	0	0	0	V	1
V_{IH}	Logic "1" Voltage All Inputs	2.2		$V_{CC} + 0.3V$	V	1
V_{IL}	Logic "0" Voltage All Inputs	-0.3		0.8	V	1

DC ELECTRICAL CHARACTERISTICS

(0°C ≤ T_A ≤ +70°C)

SYMBOL	PARAMETER		MIN	MAX	UNIT	NOTE
I_{CC1}	Average V_{CC} Power Supply Current			70	mA	6
I_{SB}	TTL Standby Current ($\bar{E} = V_{IH}$)			3	mA	7
I_{SB1}	CMOS Standby Current ($\bar{E} = V_{CC} - 0.2V$)	MK48256		1	mA	8
		MK48256L		100	μA	8
I_{LI}	Input Leakage Current (Any Input)		-1	+1	μA	2
I_{LO}	Output Leakage Current		-2	+2	μA	2
V_{OH}	Output Logic "1" Voltage ($I_{OUT} = -4.0$ mA)		2.4		V	1
V_{OL}	Output Logic "0" Voltage ($I_{OUT} = +8.0$ mA)			0.4	V	1

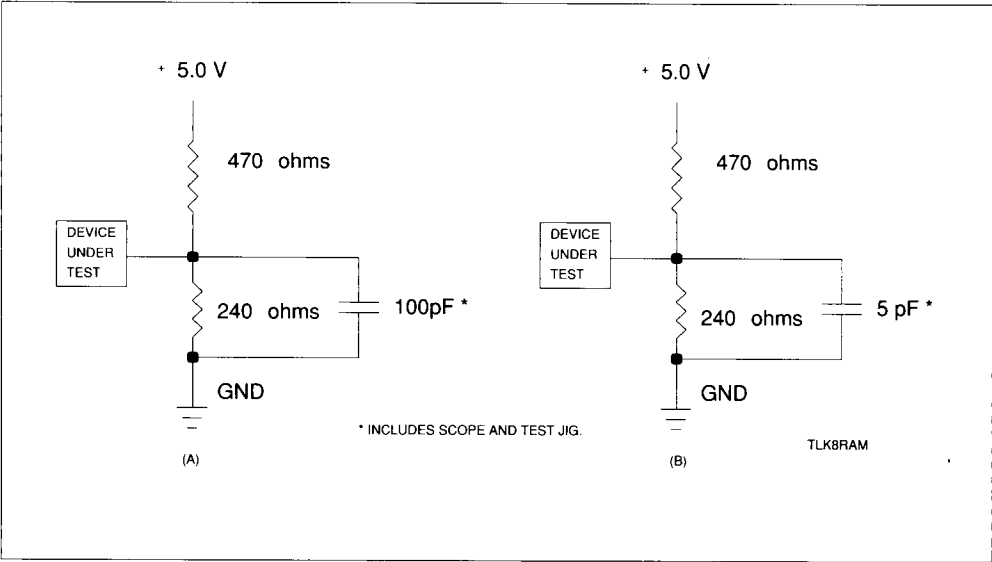
- NOTES :
1. All voltages references to Ground.
 2. Measured with $V_{SS} \leq V \leq V_{CC}$ and outputs deselected.
 6. I_{CC1} measured with outputs open, V_{CC} max ; f = min.duty cycle 100%.
 7. $\bar{E} = V_{IH}$, all other inputs = don't care ; f = 0
 8. $V_{CC}(\text{max}) \geq \bar{E} \geq V_{CC} - 0.3V$, all other inputs = don't care ; f = 0.

AC TEST CONDITIONS

Input Levels	GND to 3.0 V
Transition Time	1.5 ns
Input and Output Signal Timing Reference Level	1.5 Volts
Ambient Temperature	0°C to 70°C
V _{CC}	5.0V ± 10%

Note : ± 5% V-bump test is employed for t_{AVQV} only.

Figure 8 : Output Load Diagram



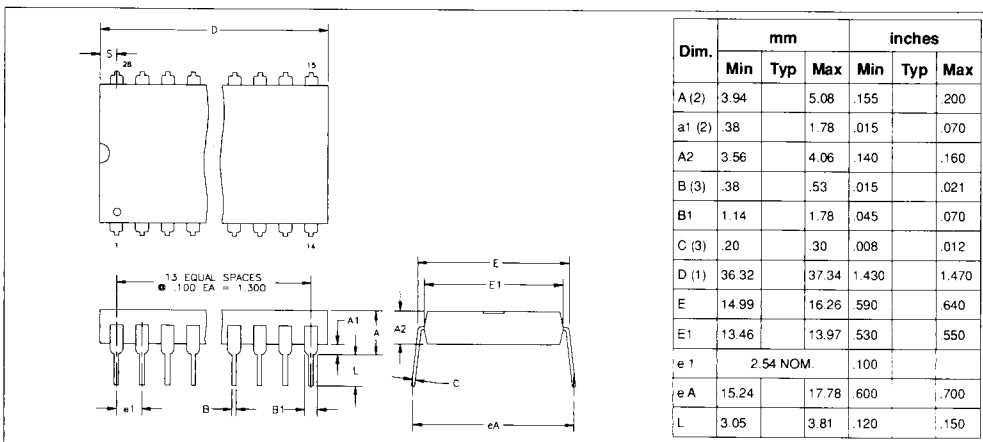
CAPACITANCE (TA = 25°C, f = 1.0 MHz)

Symbol	Parameter	Max	Unit	Note
C _I	Capacitance on all pins (except DQ)	8.0	pF	10
C _{DQ}	Capacitance on DQ pins	10.0	pF	3,10

- NOTES : 3. Output buffer is deselected.
10. Capacitances are sampled and not 100 % tested.

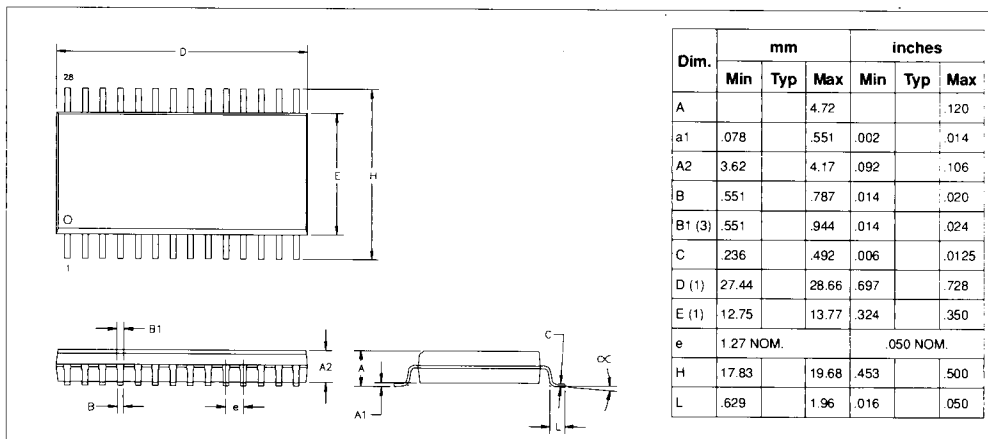
MECHANICAL INFORMATION

Figure 9 : Plastic PDIP28



- NOTES : 1. Overall length includes .010 IN. Flash on either end of the package.
 2. Package stand off to be measured per jeDEC requirements.
 3. The maximum limit shall be increased by .003 IN. When solder lead finish is specified.

Figure 10 : Plastic PSO28



- NOTES : 1. Overall length and width dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .006 per side.
 2. Formed leads shall be planar with respect to one another within .004 at seating plane.
 3. B1 is to allow for positive dambar protrusion.

ORDERING INFORMATION

PART NUMBER	ACCESS TIME	PACKAGE TYPE	TEMPERATURE RANGE
MK48256N-100	100ns	28 PIN 600 Mil. Plastic DIP	0°C to 70°C
MK48256N-120	120ns	28 PIN 600 Mil. Plastic DIP	0°C to 70°C
MK48256LN-100	100ns	28 PIN 600 Mil. Plastic DIP	0°C to 70°C
MK48256LN-120	120ns	28 PIN 600 Mil. Plastic DIP	0°C to 70°C
MK48256S-100	100ns	28 PIN 330 mil. PSO	0°C to 70°C
MK48256S-120	120ns	28 PIN 330 mil. PSO	0°C to 70°C
MK48256LS-100	100ns	28 PIN 330 mil. PSO	0°C to 70°C
MK48256LS-100	120 ns	28 PIN 330 mil. PSO	0°C to 70°C

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